



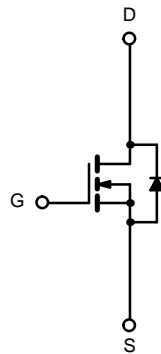
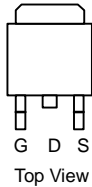
N-Channel 200-V (D-S) 175°C MOSFET

PRODUCT SUMMARY		
$V_{(BR)DSS}$ (V)	$r_{DS(on)}$ (Ω)	I_D (A)
200	0.270 @ $V_{GS} = 10$ V	9
	0.300 @ $V_{GS} = 6$ V	8.5

FEATURES

- TrenchFET® Power MOSFETS
- 175°C Junction Temperature
- New Low Thermal Resistance Package

TO-263



N-Channel MOSFET

Ordering Information: SUM09N20-270

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)				
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V_{DS}	200	V	
Gate-Source Voltage	V_{GS}	± 20		
Continuous Drain Current ($T_J = 175^\circ\text{C}$)	I_D	$T_C = 25^\circ\text{C}$	9	A
		$T_C = 125^\circ\text{C}$	5.2	
Pulsed Drain Current	I_{DM}	10		
Avalanche Current	I_{AR}	7		
Repetitive Avalanche Energy ^a	L = 0.1 mH	E_{AR}	2.45	mJ
Maximum Power Dissipation ^a	$T_C = 25^\circ\text{C}$ $T_A = 25^\circ\text{C}^c$	P_D	60 ^b	W
			3.75	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 175	$^\circ\text{C}$	

THERMAL RESISTANCE RATINGS			
Parameter	Symbol	Limit	Unit
Junction-to-Ambient (PCB Mount) ^c	R_{thJA}	40	$^\circ\text{C/W}$
Junction-to-Case (Drain)	R_{thJC}	2.5	

Notes

- Duty cycle $\leq 1\%$.
- See SOA curve for voltage derating.
- When mounted on 1" square PCB (FR-4 material).

SPECIFICATIONS (T _J = 25 °C UNLESS OTHERWISE NOTED)						
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{DS} = 0 V, I _D = 250 μA	200			V
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	2		4	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±20 V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 160 V, V _{GS} = 0 V			1	μA
		V _{DS} = 160 V, V _{GS} = 0 V, T _J = 125 °C			50	
		V _{DS} = 160 V, V _{GS} = 0 V, T _J = 175 °C			250	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	10			A
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = 10 V, I _D = 5 A		0.216	0.270	Ω
		V _{GS} = 10 V, I _D = 5 A, T _J = 125 °C			0.54	
		V _{GS} = 10 V, I _D = 5 A, T _J = 175 °C			0.71	
		V _{GS} = 6 V, I _D = 5 A		0.240	0.300	
Forward Transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 5 A		15		S
Dynamic^b						
Input Capacitance	C _{iSS}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		580		pF
Output Capacitance	C _{oss}			75		
Reverse Transfer Capacitance	C _{rSS}			30		
Total Gate Charge ^c	Q _g	V _{DS} = 100 V, V _{GS} = 10 V, I _D = 10 A		11	17	nC
Gate-Source Charge ^c	Q _{gs}			2.7		
Gate-Drain Charge ^c	Q _{gd}			4		
Gate Resistance	R _G			4.0		Ω
Turn-On Delay Time ^c	t _{d(on)}	V _{DD} = 100 V, R _L = 10 Ω I _D ≅ 10 A, V _{GEN} = 10 V, R _G = 2.5 Ω		10	15	ns
Rise Time ^c	t _r			35	55	
Turn-Off Delay Time ^c	t _{d(off)}			25	40	
Fall Time ^c	t _f			40	60	
Source-Drain Diode Ratings and Characteristics (T_C = 25 °C)^b						
Continuous Current	I _S				9	A
Pulsed Current	I _{SM}				10	
Forward Voltage ^a	V _{SD}	I _F = 10 A, V _{GS} = 0 V		0.9	1.5	V
Reverse Recovery Time	t _{rr}	I _F = 10 A, di/dt = 100 A/μs		100	150	ns
Peak Reverse Recovery Current	I _{RM(REC)}			5	8	A
Reverse Recovery Charge	Q _{rr}			0.25	0.6	μC

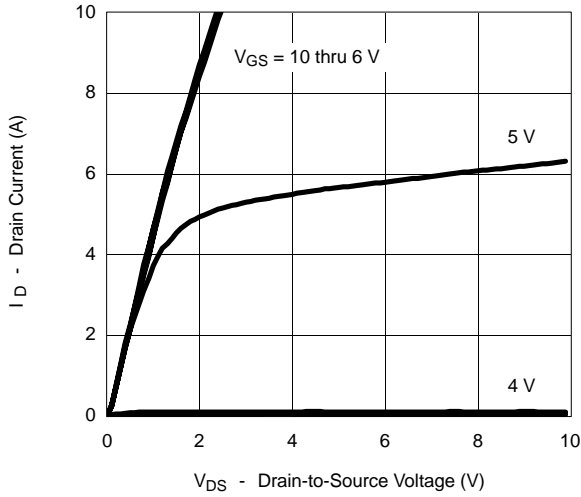
Notes

- Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
- Guaranteed by design, not subject to production testing.
- Independent of operating temperature.

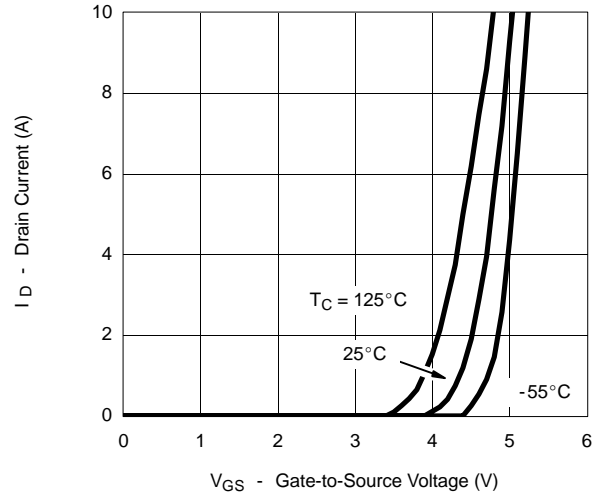


TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

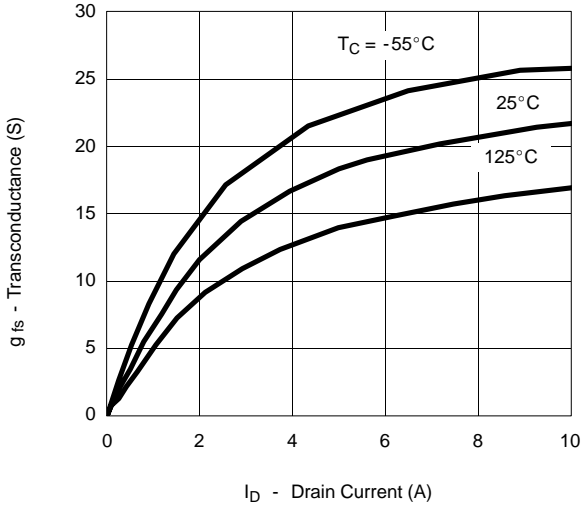
Output Characteristics



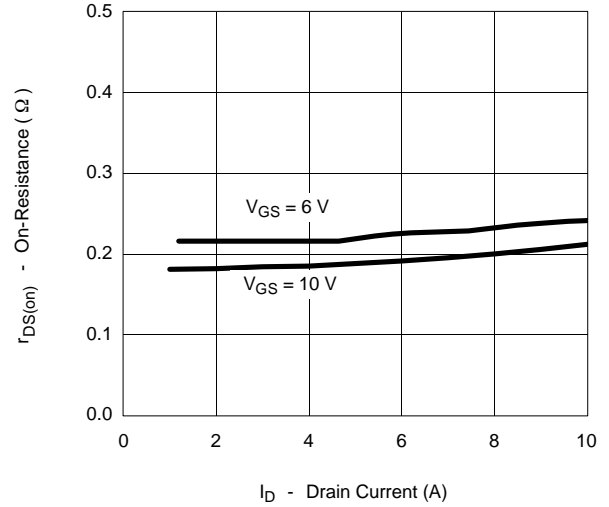
Transfer Characteristics



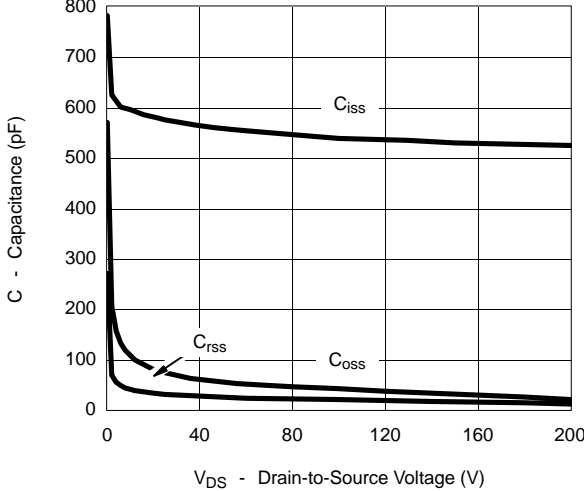
Transconductance



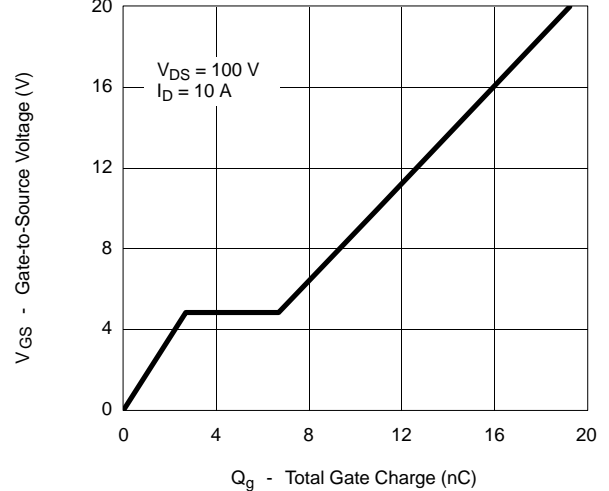
On-Resistance vs. Drain Current



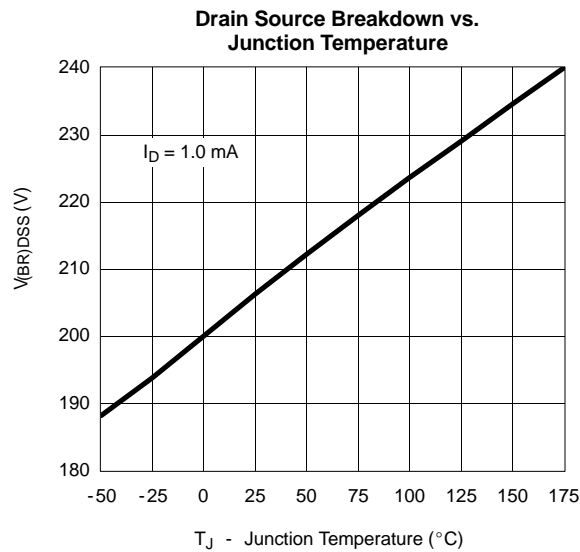
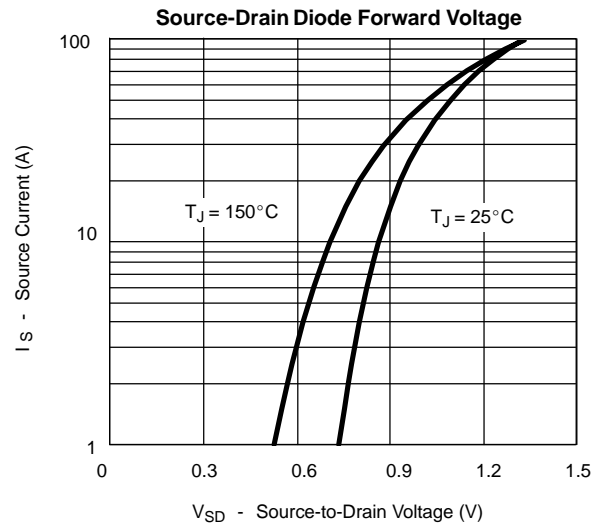
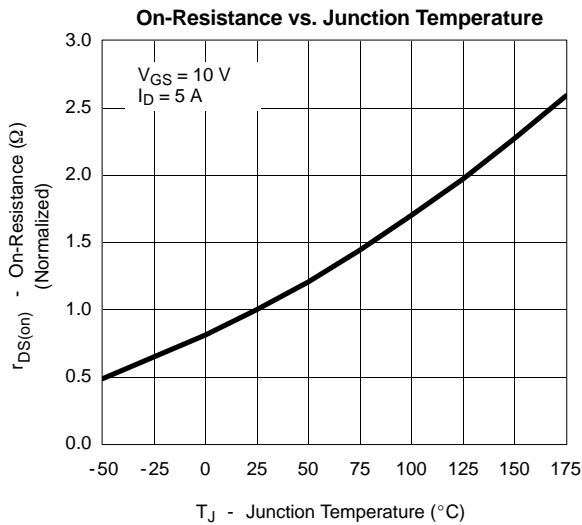
Capacitance



Gate Charge



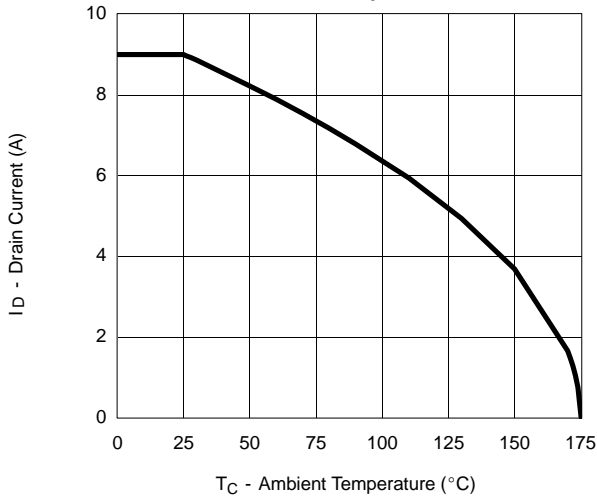
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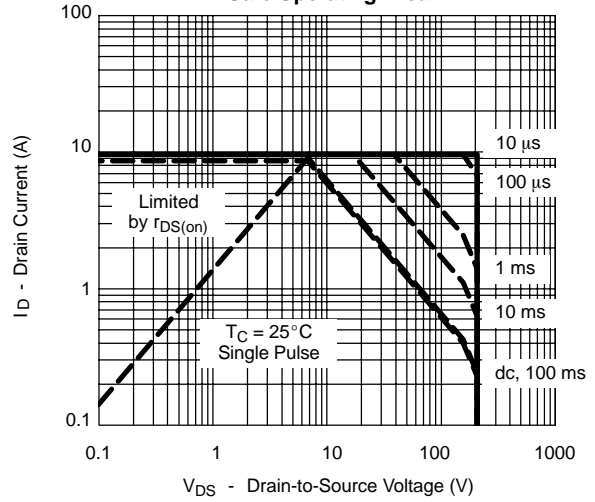


THERMAL RATINGS

Maximum Avalanche and Drain Current vs. Case Temperature



Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case

